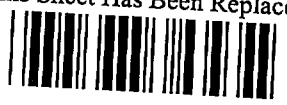
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ABSTRACT OF THE DISCLOSURE

EXPOSED HEAT SPREADER WITH SEAL RING

A semiconductor package (100) comprising: (a) at least one semiconductor device (102); (b) a metal heat spreader (200; 300; 400) that has at least one surface (201; 306; 409) exposed to ambient and the perimeter of that exposed surface having a seal ring border (203; 307; 407); (c) a leadframe (105) having a plurality of inner and outer leads (103), said inner leads (103) interconnected to said semiconductor device; and (d) a molding resin (101) encapsulating said semiconductor device, said inner leads (103) of said leadframe (105) and all of the heat spreader (200; 300; 400) except that exposed surface having the seal ring border (203; 307; 407). (Figure 2)